



## ISLPED 2023 Design Contest Award

Awarded to the submission titled

### SmartHeaP - A High-level Programmable, Low Power, and Mixed-Signal Hearing Aid SoC in 22nm FD-SOI

Jens Karrenbauer, Simon Klein, Sven Schönwald, Lukas  
Gerlach, Meinolf Blawat, Jens Benndorf, and Holger Blume

(Institute of Microelectronic Systems, Leibniz University Hannover and  
Dream Chip Technologies GmbH)

TU Wien

August 8, 2023

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